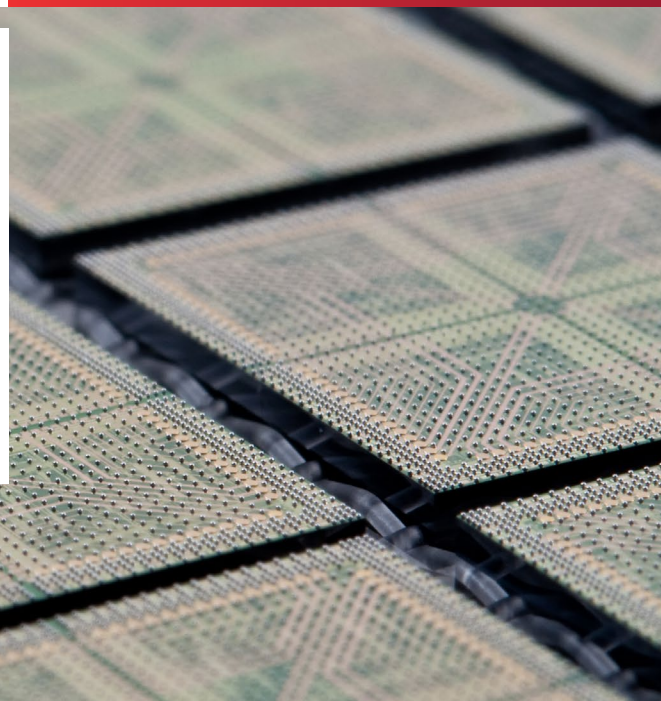


Wafer Dicing and Backgrinding Services

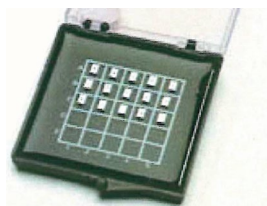
Whether you are a Fabless Semiconductor company needing a complete turnkey packaging and assembly solution for your new designs, or an Integrated Device Manufacturer with internal prototype assembly capability, QP Technologies can provide wafer and die preparation services to meet your requirements.



Capabilities:

- Wafer Dicing up to 300mm
- Backgrinding
- Silicon, Quartz, Glass, Ceramin, Laminates, etc.
- Multiproject Wafers (MPW)
- Die Sort into Various Media (Gel-Pak®, Waffle Pack)
- Same-Day Service Available
- Prototype to Medium Volume
- Cleanroom Environment
- Outstanding Quality and Customer Service

- **Wafer Dicing** - DISCO automatic equipment will precisely dice your wafers or substrates, including multiproject or “pizza” wafers. Kerf widths as narrow as 15µm. Automatic kerf width/chip-out monitoring.
- **Backgrinding** - Wafers can be thinned down to 75µm to accommodate the latest package technology and stacked die applications.
- **Pick and Place** - Have your die sorted into Gel-Paks® or waffle packs.
- **Quick-Turn Service** - When you need to meet a project or customer deadline, you can count on QP Technologies’ reliable on-time delivery options including same-day expedited service. In fact, we can receive a wafer in the morning and ship completely assembled devices by the end of the day.
- **Remolding** - Prototypes meet JEDEC standards for test socket and auto-handling compatibility.
- **Branding** - Pad-print a logo, part number and/or date code for clear identification.



When you require a full turnkey solution of production-quality prototype parts for internal testing or customer samples, QP Technologies is the answer. Services include Wafer Backgrinding and Dicing, Package Procurement and Open Cavity Preparation, Die Attach, Wire Bonding, Encapsulation, Remolding and Marking.